

EV Group expands collaboration with ITRI on heterogeneous integration process development – September 1, 2022

EVG announced that it has expanded its collaboration with the ITRI, one of the world's leading applied technology research institutes based in Hsinchu, Taiwan, on developing advanced heterogeneous integration processes. With the support of the DoIT of the MOEA, Taiwan, ITRI established the Heterogeneous Integration Chip-let System Package Alliance (Hi-CHIP) to help create an ecosystem covering package design, testing and verification, and pilot production, to achieve the goal of supply chain localization and expand business opportunities. As a member of the Hi-Chip Alliance, EVG has provided several of its most advanced wafer bonding and lithography systems, including the LITHOSCALE® maskless exposure lithography system, EVG®850 DB automated debonding system, and GEMINI®FB hybrid bonding system.



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